Series 350000-10-HT High-Temperature SOIC-to-DIP Adapter

FEATURES
• A cost-effective means of upgrading to SOIC without changing your PCB layout
• Available on 0.300 [7.62] centers. Consult Data Sheet 18011 for Adapters on 0.400 [10.16] or 0.600 [15.24] centers

GENERAL SPECIFICATIONS
• BOARD MATERIAL: 0.062 [1.58] thick Polyimide, Tg 260°C with 1-oz. Cu traces, both sides
• PADS: finished with white Sn
• PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
• PIN PLATING: 200µ [5.08µ] Sn/Pb 93/7 per ASTM B579-73 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-2790
• OPERATING TEMPERATURE: 200°C max.

MOUNTING CONSIDERATIONS
SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.

CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. NOTE: Aries reserves the right to change product general specifications without notice.

ALL DIMENSIONS: INCHES [MILLIMETERS]
ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED
“A” = NO. OF PINS PER ROW x 0.100 [2.54]
“D” = (NO. OF PINS PER ROW -1) x 0.100 [2.54]
AVAILABLE IN PANELIZED FORM WITH OR WITHOUT CUSTOMER-SUPPLIED DEVICES MOUNTED. CONSULT FACTORY
CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

ORDERING INFORMATION
See Table below for P/Ns

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<td>08-350000-10-HT</td>
<td>8</td>
<td>SOIC</td>
<td>0.450 [11.43]</td>
<td>0.300 [7.62]</td>
<td>0.420 [10.67]</td>
<td>0.138 [3.51]</td>
<td>0.150 [3.81]</td>
<td>0.180 [4.57]</td>
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